

**Change to Assembly Die Bond Epoxy and Mold Compound Materials for Generic
AD5532 CSP_BGA Products**

**Qualification Result Summary
for AD5532 CSP_BGA with G7730L/CRM1525**

QUALIFICATION RESULT			
TEST	SPECIFICATION	SAMPLE SIZE	RESULTS
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	3 x 77	Pass
Unbiased Highly Accelerated Stress Test (uHAST)*	JEDEC <i>JESD22-A118</i>	3 x 77	Pass
Highly Accelerated Stress Test (HAST)*	JEDEC <i>JESD22-A110</i>	3 x 60	Pass
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	3 x 50	Pass
High Temperature Operation Life (HTOL)	JEDEC <i>JESD22-A108</i>	2 x 54	Pass

*Preconditioned per JEDEC/IPC J-STD-020